



PRESS RELEASE

BE Semiconductor Industries N.V. Announces Results of 2020 Annual General Meeting of Shareholders

Duiven, the Netherlands, April 30, 2020 - BE Semiconductor Industries N.V. (the "Company" or "Beside") (Euronext Amsterdam: BESI; OTC: BESIY, Nasdaq International Designation), a leading manufacturer of assembly equipment for the semiconductor industry, today announced results of its Annual General Meeting of Shareholders ("AGM").

All items on the Agenda received a majority of votes in favor. Item 7a of the Agenda received also majority vote, however failed to receive the 75% threshold required under the new legislation implementing the EU Shareholder Rights' Directive. In view of the new legislation, Beside will nonetheless take into account the proposed Remuneration Principles and Procedures underlying the Remuneration Policy 2020-2023 for the Board of Management as approved at the 2019 AGM and the Remuneration Policy for the Supervisory Board as approved at the AGM today.

Dividend 2019

The dividend proposal of € 1.01 per ordinary share for the 2019 financial year was approved at the AGM. Such dividend will be paid out wholly in cash. Payments will commence as of May 8, 2020. The following time-table will be applicable with respect to the dividend payment:

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|------------------------|---|
| • May 5, 2020 | Ex-dividend quotation |
| • May 6, 2020 | Record date for dividend eligibility (after market close) |
| • Starting May 8, 2020 | Payment of cash dividend |

Holders of ordinary shares will receive the dividend through their bank or broker in whose custody their ordinary shares are held on May 6, 2020 close of business (record date). The dividend will be made payable to them as of May 8, 2020 through ABN AMRO Bank N.V.

About Beside

Beside is a leading supplier of semiconductor assembly equipment for the global semiconductor and electronics industries offering high levels of accuracy, productivity and reliability at a low cost of ownership. The Company develops leading edge assembly processes and equipment for leadframe, substrate and wafer level packaging applications in a wide range of end-user markets including electronics, mobile internet, cloud server, computing, automotive, industrial, LED and solar energy. Customers are primarily leading semiconductor manufacturers, assembly subcontractors and electronics and industrial companies. Beside's ordinary shares are listed on Euronext Amsterdam (symbol: BESI). Its Level 1 ADRs are listed on the OTC markets (symbol: BESIY, Nasdaq International Designation) and its headquarters are located in Duiven, the Netherlands. For more information, please visit our website at www.beside.com.

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